

PATENT ABSTRACTS OF JAPAN

(11) Publication number : 2002-204077

(43) Date of publication of application : 19.07.2002

(51) Int.Cl.

H05K 3/46

H01G 4/12

H01G 4/40

(21) Application number : 2000-403144

(71) Applicant : NGK SPARK PLUG CO LTD

(22) Date of filing : 28.12.2000

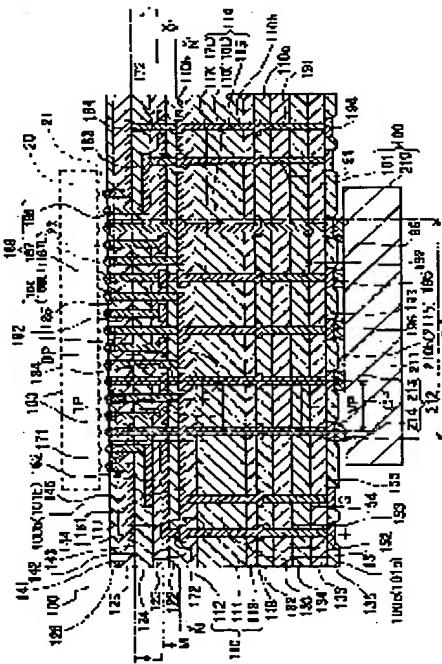
(72) Inventor : SUGIMOTO YASUHIRO
KURODA MASAO
KIMURA YUKIHIRO

(54) WIRING SUBSTRATE, WIRING SUBSTRATE MAIN BODY, AND CHIP CAPACITOR

(57) Abstract:

PROBLEM TO BE SOLVED: To provide wiring substrate having an electronic component such as an IC chip mounted on a major surface of a main body of the substrate having a core insulating layer, which facilitates connection between terminals such as power and grounding terminals and through-hole conductors formed in the core insulating layer.

SOLUTION: A wiring substrate 100 having an electronic component 20 mounted on a major surface 100b has a core insulating layer 110, and the major surface has first and second connection bumps 187 and 188 alternately arranged on the major surface in a lattice form to be formed as power and grounding terminals. Soled first and second conversion conductor layers 161 and 162 are provided between through-hole conductors 114 formed in the core insulating layer 110, and via conductors 182 and 183 on the major surface are extended from first and second bumps 187 and 188 to be connected to the first and second conductor layers. A core-side via conductor 184 is extended to be connected directly from first and second through-hole conductors 117 and 118 thereto.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]